



Application Number: 10/654,167

Docket: DT-024-US-01
(33321/US)

In the Claims

The following list of pending claims replace any prior list of claims.

1. (Original) A hot melt adhesive composition comprising:
 - (a) an ethylene methyl methacrylate copolymer; and
 - (b) a tackifying resin,with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
2. (Original) The composition of claim 1 further comprising an oil.
3. (Original) The composition of claim 2 further comprising a wax.
4. (Original) The composition of claim 3 further comprising an antioxidant.
5. (Original) The composition of claim 4 further comprising a copolymer.
6. (Original) The composition of claim 5 further comprising a block copolymer.
7. (Original) The composition of claim 1 further comprising a wax.
8. (Original) The composition of claim 7 further comprising a block copolymer.
9. (Original) A package formulation comprising:
 - (a) the composition of claim 1; and
 - (b) instructions for application of the composition to a substrate.
10. (Withdrawn) A method of making the composition of claim 1.
11. (Original) A hot melt adhesive composition consisting essentially of:
 - (a) an ethylene methyl methacrylate copolymer; and
 - (b) a tackifying resin.
12. (Original) The composition of claim 11 further consisting essentially of an oil.

13. (Original) The composition of claim 12 further consisting essentially of a wax.
14. (Original) The composition of claim 13 further consisting essentially of an antioxidant.
15. (Original) The composition of claim 14 further consisting essentially of a block copolymer.
16. (Original) The composition of claim 11 further consisting essentially of a wax.
17. (Original) The composition of claim 16 further consisting essentially of a block copolymer.
18. (Withdrawn) A method of making the composition of claim 11.
19. (Withdrawn) A method of using a hot melt adhesive composition comprising:
 (a) providing a hot melt adhesive composition comprising:
 (i) an ethylene methyl methacrylate copolymer; and
 (ii) a tackifying resin,
 with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate; and
 (b) applying the composition to a substrate.
20. (Withdrawn) The method of claim 19 wherein the method is a method of using the hot melt adhesive for book binding.